

Date of Response: December 5, 2005

SPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Appl. No. : **10/734,195**
Applicant : **Kwun-Yao Ho et al.**
Filed : **December 15, 2003**
Title : **HIGH-DENSITY MULTICHIP MODULE**
PACKAGE
TC/A.U. : **2813**
Examiner : **BRYANT, DELORIS S**
Docket No. : **025796-00014**

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Official Action mailed September 14, 2005. Applicants respectfully request that the Examiner reconsider the amended application according to the following remarks.

Please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begin on page 4 of this paper.

Remarks/Arguments begin on page 7 of this paper.